X11SPW-TF



WIO VROC support

Key Features

- 1. 2nd Gen Intel® Xeon® Scalable Processors and Intel® Xeon® Scalable Processors, , Single Socket LGA-3647 (Socket P) supported, CPU TDP support Up to 205W TDP
- 2. Intel® C622 chipset
- 3. Up to 1.5TB 3DS ECC RDIMM, DDR4-2933MHz; Up to 1.5TB 3DS ECC LRDIMM, DDR4-2933MHz, in 6 DIMM slots
- 4. M.2 NGFF connector

M.2 Interface: PCI-E 3.0 x4 and SATA

Form Factor: 2280, 22110

Key: M-Key

Double Height Connector

- 5. Expansion slots:
 - 1 PCI-E 3.0 x8 (in x16), 1 PCI-E 3.0 x32 Left Riser slot
- 6. 2 10GbE LAN ports
- 7. 10 SATA3 (6Gbps) via C622
- 8. I/O: 1 VGA, 2 COM, TPM header
- 9. 2 SuperDOM with built-in power

Specifications

Product SKUs		Expansion Slots		
MBD-X11SPW- TF	■ X11SPW-TF	PCI-E	1 PCI-E 3.0 x8 (in x16 slot),1 PCI-E 3.0 x32 Left Riser Slot	
Physical Stats		M.2	M.2 Interface: PCI-E 3.0 x4; SATAForm Factor: 2280, 22110Key: M-Key	
Form Factor	■ Proprietary WIO			
Dimension	■ 8" x 13" (20.32cm x 33.02cm)	System BIOS		
		BIOS Type	■ AMI UEFI	
Processor		BIOS Features	■ ACPI 6.0	
CPU	2nd Gen Intel® Xeon® Scalable Processors and Intel® Xeon® Scalable Processors		RTC (Real Time Clock) WakeupSMBIOS 3.0 or later	
	 Single Socket LGA-3647 (Socket P) supported, CPU TDP supports Up to 205W TDP 	Management Software	■ SuperDoctor® 5, NMI, <u>SUM</u> , KVM	
Core	■ Up to 28 cores ■ BIOS version 3.0a or above is	Software	with dedicated LAN, <u>SPM</u> , Intel® Node Manager, <u>IPMI2.0</u> , Watchdog	
Note	required to support 2nd Generation Intel Xeon Scalable Processors-SP	Power Configurations	 Power-on mode for AC power recovery, ACPI Power Management 	
	BIOS version 3.2 or above is required to support 2nd Gen Intel® Xeon® Scalable processors (codenamed Cascade Lake-R)	PC Health Monitoring		
System Memory Memory Capacity	■ 6 DIMM slots ■ Up to 1.5TB 3DS ECC LRDIMM,	Voltage	VBAT, Supports system management utility, Monitors CPU voltages, HT, Chassis intrusion header, 3.3V standby, +5V standby, +5V, +3.3V, +12V, +1.8V, 7-fan status	
Maman, Tuna	DDR4-2933MHz; Up to 1.5TB 3DS ECC RDIMM, DDR4-2933MHz	LED	 UID/Remote UID Suspend static indicator LED CPU / System Overheat LED 	
Memory Type	 2933/2666/2400/2133MHz ECC DDR4 LRDIMM (3DS), RDIMM (3DS) 	Temperature	CPU thermal trip support PECI	
DIMM Sizes	 LRDIMM: 32GB, 64GB, 128GB RDIMM: 8GB, 16GB, 32GB, 64GB 	FAN	7x 4-pin fan headers (up to 7 fans)System level control	
Memory Voltage	■ 1.2V		PWM fan speed controlFan speed control	
Error Detection	■ Corrects single-bit errors	Other Features	Overheat LED indication WOL	
On-Board Devices		Other reatures	UIDRoHSControl of power-on for recovery	
Chipset SATA	■ Intel® C622 ■ Intel® C622 controller for 10 SATA3		from AC power loss ACPI power management	
	(6 Gbps) ports; RAID 0,1,5,10			
IPMI	ASPEED AST2500	Operating Environ	nment	
Graphics Network Controllers	 ASPEED AST2500 BMC Dual LAN with 10GBase-T with Intel® X722 + X557 	Operating Temperature Range	■ 0°C - 50°C (32°F - 122°F)	
Input / Output		Non-Operating Temperature Range	■ -40°C - 70°C (-40°F - 158°F)	
SATA	■ 10 SATA3 (6Gbps) port(s)			
LAN	■ 2 RJ45 10GBase-T ports			

USB	 3 USB 3 port(s) (1 Type A; 2 via header) 7 USB 2.0 port(s) (2 rear; 5 via header) 2 USB 3.0 port(s) (2 rear)
Video Output	■ 1 VGA port(s)
Serial Port	2 COM Port(s) (1 header; 1 rear)
DOM	 2 SATA <u>DOM</u> (Disk on Module) power connector support
TPM	■ 1 TPM Header

Operating Relative Humidity Range	■ 8% - 90% (non-condensing)
Non Operating Relative Humidity Range	■ 5% - 95% (non-condensing)

Parts List

Parts List (Bulk Package)			
Name	Part Number	Qty	Description
Motherboard	MBD-X11SPW-TF	1	X11SPW-TF Motherboard
I/O Cables	CBL-0044L • @Store	2	57.5CM SATA FLAT S-S PBF

Optional Parts List			
Name	Part Number	Qty	Description
TPM security module	AOM-TPM-9671H AOM-TPM-9670H AOM-TPM-9671V AOM-TPM-9670V	1 1 1 1	SPI capable TPM 1.2 with Infineon 9670 controller with horizontal form factor SPI capable TPM 2.0 with Infineon 9670 controller with horizontal form factor SPI capable TPM 1.2 with Infineon 9670 controller with vertical form factor
			SPI capable TPM 2.0 with Infineon 9670 controller with vertical form factor

Chassis (Optimized for X11SPW-TF)

Embedded Compact	10	20	3U	Mid/Mini-Tower	4U/Tower
	<u>SCLA15TQC-</u> <u>563W</u> ■ <u>SC815TQC-</u> <u>605WB</u> <u>SCLA15TQC-</u> <u>R504W</u> ■ <u>SC815TQC-</u> <u>R504WB</u>	SC825TQ- R500WB Heatsink:SNK- P0068PS			

 Most optimized Chassis for SuperServer Configuration Blue color = Compatible
 Green color = Global SKU & Compatible
 Red dot & green color = Optimized + Global SKU

Server (Optimized for X11SPW-TF)

Server (Optimized for X113FW-1F)	
	Server Name
SYS-1019P-FHN2T	
SYS-1019P-WTR	
SYS-5019P-WT	
SYS-5019P-WTR	
SYS-5029P-WTR	
<u>SYS-E403-9P-FN2T</u>	
SYS-1019P-FRN2T	
SYS-1019P-FRDN2T	